

QMSS SERIES

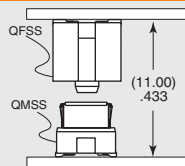
SHIELDED GROUND PLANE HEADER

Insulator Material:
Liquid Crystal Polymer
Terminal, Ground
Plane & Shield Material:
Phosphor Bronze
Plating:
Au over 50 μ " (1.27 μ m) Ni
(Tin on Ground Plane Tail)
Voltage Rating:
300 VAC mated with QFSS
Operating Temp:
-55 °C to +125 °C
RoHS Compliant:
Yes

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (026-078)
Board Stacking:
For applications requiring more
than two connectors per board,
contact ipg@samtec.com



- Headers without Alignment Pins
- 8 Power Pins/End
- 4 or 8 Power Pins/End for (2.36 mm) .093" thick board
- Guide Post
- Edge Mount
- 64 (-DP) and 104 pins per row



Some lengths, styles and options are non-standard, non-returnable.

RUGGEDIZED
— BY SAMTEC —

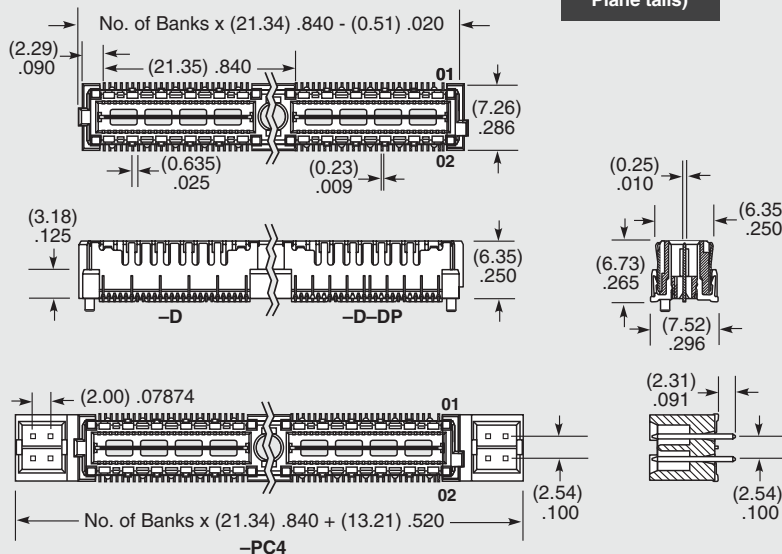
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- Integral metal plane for power or ground
- Increased insertion depth for rugged applications
- Optional Power Pins
- Grounds to shield
- Signal Pairs Differential routing
- (1.30 mm)
.051"
NOMINAL
WIPE
- PERFORMANCE**
- Jack Height

14
Gbps

Q MSS	PINS PER ROW NO. OF PAIRS	06.75	PLATING OPTION	TYPE	A	OTHER OPTION
-026, -052, -078 (52 total pins per bank 40 signals + 12 grounds to shield = -D) -016, -032, -048 (16 pairs per bank = -D-DP)			-L = 10 μ" (0.25 μm) Gold on Signal Pins, Shield and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)	-D = Single-Ended -D-DP = Differential Pair	-K = (5.50 mm) .217" DIA Polyimide film Pick & Place Pad (N/A with -PC4) -PC4 = 4 Power Pins/End (N/A with -A)	

(2.29)

No. of Banks x (21.34) .840 - (0.51) .020



See SO Series for precision machined standoffs.

*All parts within this catalog are built to Samtec's specifications.
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.*